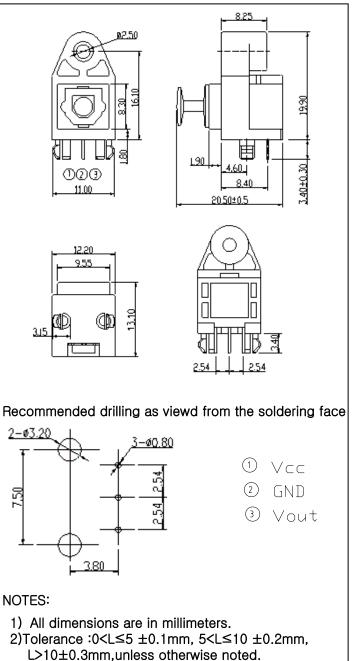
b Free				
npliant	APPRO\	AL SHE	EET	
		:		
	DEVICE NAME	: Photo Link		
	MODEL NO.	: SRX-R179A1		
	ISSUED DATE	: DEC. 07. 2012	2	
	ISSUE	REVIEW	REVIEW	APPR'D
ISSUED DEPT.			邱丽红	AMA
		TEL : +	86-755-8887830 86-755-88828221	

SEKSEMI

• Features:

- 1.Uni-directional data transmission using plastic fiber
- 2.Signal transmission speed
- 3.Operating voltage:2.4 5.5 V
- 4.Low power consumption

• Outline Dimensions:



Absolute Maximum Ratings(Ta=25℃)

			@ TA=25℃
Parameter	Symbol	Rating	Unit
Supply voltage	Vcc	-0.5 to + 5.5	V
Input voltage	Vo	Vcc+0.3V	V
Operating temperature	Topr	-20 to +70	°C
Storage temperature	Tstg	-30 to +80	°C
Soldering temperature *1	Tsol	260*	°C

*1 1 time For 5s (≤2 times) (The temperature of the PCB surface is <90℃)



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Recommended Operating Conditions:

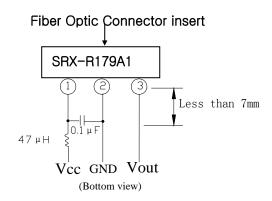
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating supply voltage	Vcc	2.4		5.5	V
Operating transfer rate (NRZ signal)	Т	0.1		13.2	Mbps

Electro-Optical Characteristics:

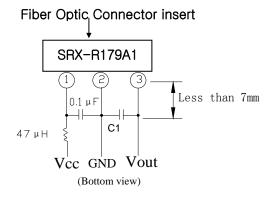
				(Ta=25℃, Vcc=3V,CL=5pf,Ip=660nm)			
NO.	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
1	Peak sensitiving wavelength	λp			660		nm
2	Receiver input optical power level	Pc	Refer to Fig. 3	-24		-13.5	dBm
3	Dissipation current	Icc	Refer to Fig. 2	3		7	mA
4	High level output voltage	V _{oH}	Refer to Fig. 1	2.1			V
5	Low level output voltage	VoL	Refer to Fig. 1		0.2	0.4	V
6	Rise time	tr	Refer to Fig. 1		8	20	ns
7	Fall time	t _f	Refer to Fig. 1		8	20	ns
8	Low \rightarrow High delay time	t _{pLH}	Refer to Fig. 1			100	ns
9	High \rightarrow Low delay time	t _{pHL}	Refer to Fig. 1			100	ns
10	Pulse width distortion	Δtw	Refer to Fig. 1	-15		+15	ns
11	Jitter	Δ tj	Refer to Fig. 1			15	ns

Recommended Connection Method

1、General application circuit for 3V



2、General application circuit for 5V



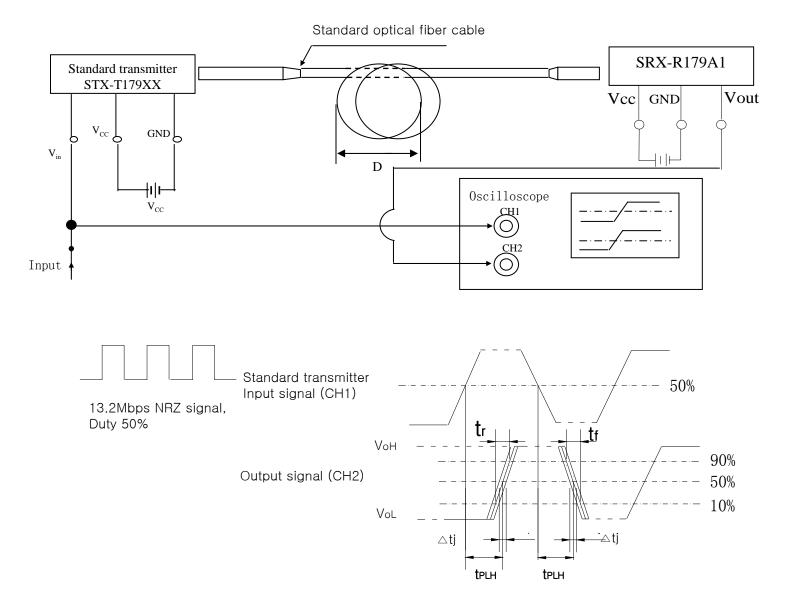
NOTES:

 For 5V application a minimum of C1=30PF capacitive loading at the Output pin is recommended. If the motherboard PCB board trace loading and the input loading of the next device exceeds 30PF, then extra capacitive loading is not needed. (Example: PCB trace loading +input device loading=10PF, then add 20PF(C1) between the Output to GND



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• Fig.1 Measuring Method of Pulse Response:



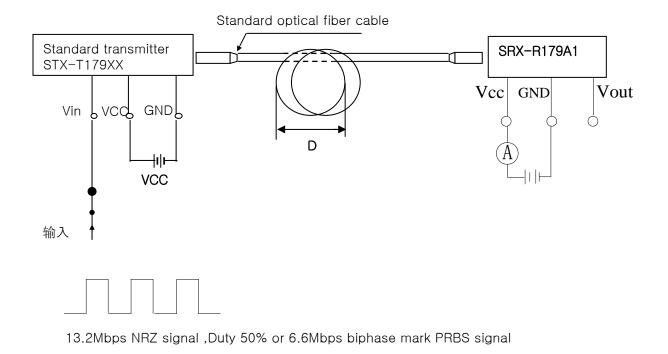
●Test item:

Test item	Symbol
Low \rightarrow High pulse delay time	t _{PLH}
High →Low pulse delay time	t _{PHL}
Rise time	t _r
Fall time	t _f
High level output voltage	V _{oH}
Low level output voltage	V _{oL}
Jitter	Δτj
Pulse width distortion($\Delta \tau \omega$ =t PHL- t PLH)	Δτω

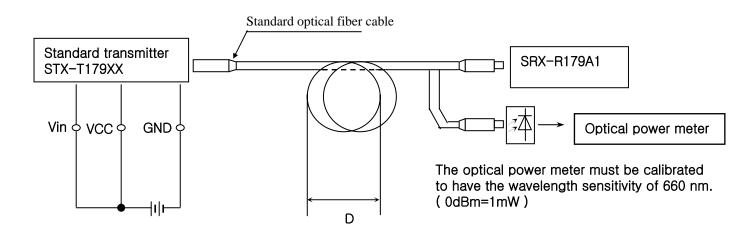


• Fig. 2 Measuring Method of Current Consumption.

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• Fig. 3 Measuring Method of Optical Output Coupling with Fiber



Notes :

(1)Vcc=3.0V

(2)To bundle up the standard fiber optic cable, make it into a loop with the diameter $D \ge 10$ cm . (3)Measured on an ammeter.

(4)The probe for the oscilloscope must be more than 1M and less than 10pF.





• RELIABILITY:

				SAMPLE NUMBER(n)
NO.	TEST ITEMS	TEST CONDITIONS	JUDGEMENT CRITERIA	SAMPLE FAILURE(c)
1	Life Test	Vcc=5V , 500H		N=10,c=0
2	High Temperature Storage	Ta=80℃±5℃, RH=85% Time=48Hrs		N=10,c=0
3	Low Temperature Storage	Ta=-30℃±5℃, Time=48Hrs		N=10,c=0
4	Temperature Cycling	Ta=-35 ℃~+85 ℃(85%RH) (30min) (30min) 20Cycles	Electro-Optical Characteristics NO.2~9 Shall	N=10,c=0
5	Falling off Tset	Take the PCB with optical fiber jack to fall-self from 1 meter high ,3cycles	be satisfied	N=10,c=0
6	Soldering Strength Test	Soldering the optic fiber chip in the PCB, Then converse swing from a object by I kg weight , 1minute		N=10,c=0
7	Low High Temperature Impact Test	Ta=-35 ℃~+85 ℃ (30min) (30min) 8Cycles		N=10,c=0
8	Soldering Ability Test	Ta=260 ℃±5 ℃,5seconds	95% or more of the solder area is covered with solder,	N=10,c=0
9	Soldering Heat	Ta=260 ℃±5 ℃,10seconds	and Electro-Optical Characteristics NO.2~9 shall be satisfied	N=10,c=0



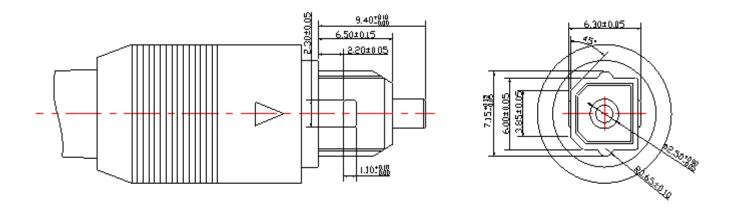


MATERIAL DESCRIPTION

No.	Name	Material
1	HOUSING	ABS
2	PLUG	ABS
3	COVER	ABS

• RECOMMENDED:

BE SUIT WITH THIS OPTICAL DIGITAL CABLE







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